

Fig. 1. Optical sensors with a backside acquisition of light using deep trench isolator to isolate pixels.

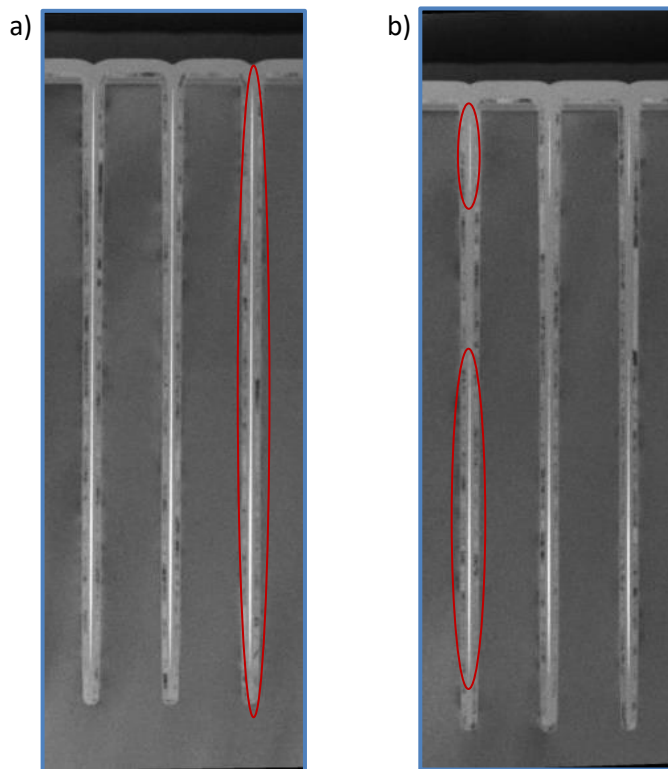


Fig. 2. Cross-sectional TEM images of deep trenches after the deposition of SiO_2 thin film using (a) Sub-Atmospheric Chemical Vapor Deposition (SACVD) and (b) Plasma Enhanced Atomic Layer Deposition (PEALD). The presence of voids in the filling is highlighted in red.